

Data Sheet

August 16, 2005

专业PCB打样工厂

FN7003.2

24小时加急出先 上7535

# Monolithic 350mA Step-Down Regulator

The EL7535 is a synchronous, integrated FET 350mA stepdown regulator in a MSOP10 package. The regulator is internally compensated, which makes it possible to use just five tiny external components to form a complete DC/DC converter. The regulator operates with an input voltage range from 2.5V to 6V, which accommodates supplies of 3.3V, 5V, or a Li-Ion battery source. The output can be externally set from 0.8V to V<sub>IN</sub> with a resistive divider.

The EL7535 features PWM mode control. The operating frequency is typically 1.4MHz. Additional features include <1µA shut-down current, short-circuit protection, and over-temperature protection.

The EL7535 is available in the 10-pin MSOP package and is specified for operation over the full -40°C to +85°C temperature range.

PART NUMBER (BRAND)	PACKAGE	TAPE & REEL	PKG. DWG. #
EL7 <mark>535IY</mark> (a)	10-Pin MSOP	-	MDP0043
EL7535IY-T7 (a)	10-Pin MSOP	7"	MDP0043
EL7535IY-T13 (a)	10-Pin MSOP	13"	MDP0043
EL7535IYZ (BAACA) (Note)	10-Pin MSOP (Pb-free)	子币	MDP0043
EL7535IYZ-T7 (BAACA) (Note)	10-Pin MSOP (Pb-free)	7"	MDP0043
EL7 <mark>535IYZ-T13</mark> (BAACA) (Note)	10-Pin MSOP (Pb-free)	13"	MDP0043

### **Ordering Information**

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

### Features

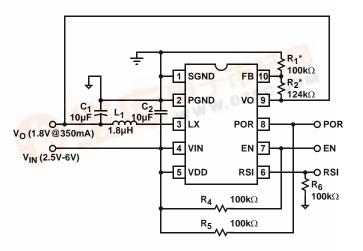
- Extremely small 350mA DC/DC converter
- Max height 1.1mm MSOP10 package
- Possibly uses only five tiny external components with fixed output
- · Power-On-Reset output (POR)
- · Internally-compensated voltage mode controller
- · Up to 94% efficiency
- <1µA shut-down current</li>
- Overcurrent and over-temperature protection
- Pb-Free plus anneal available (RoHS compliant)

### Applications

- PDA and pocket PC computers
- · Bar code readers
- Cellular phones
- Portable test equipment
- Li-lon battery powered devices
- Small form factor (SFP) modules

## **Pinout and Typical Application Diagram**

EL7535 (10-PIN MSOP) TOP VIEW



\* FOR VARIABLE OUTPUT VOLTAGE: V<sub>O</sub> = 0.8V \* (1 + R<sub>2</sub> / R<sub>1</sub>)



## Absolute Maximum Ratings $(T_A = 25^{\circ}C)$

V <sub>IN</sub> , V <sub>DD</sub> , POR to SGND	0.3V to +6.5V
LX to PGND	′ to (V <sub>IN</sub> + +0.3V)
RSI, EN, V <sub>O</sub> , FB to SGND	' to (V <sub>IN</sub> + +0.3V)
PGND to SGND	0.3V to +0.3V

Peak Output Current	
Operating Ambient Temperature	40°C to +85°C
Storage Temperature	65°C to +150°C
Junction Temperature	+145°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore:  $T_J = T_C = T_A$ 

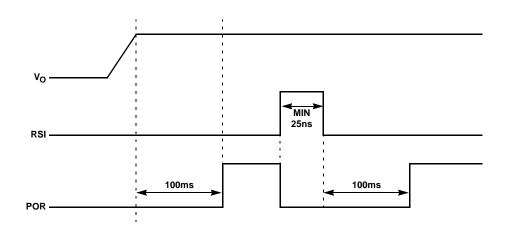
 $\label{eq:expectations} Electrical Specifications \quad V_{DD}$  =  $V_{IN}$  =  $V_{EN}$  = 3.3V, C1 = C2 = 10 \mu F, L = 1.8 \mu H, V\_O = 1.8V, unless otherwise specified.

PARAMETER	DESCRIPTION CONDITIONS		MIN	TYP	MAX	UNIT
DC CHARACTE	RISTICS		·			
V <sub>FB</sub>	Feedback Input Voltage		790 800 810		mV	
I <sub>FB</sub>	Feedback Input Current				250	nA
V <sub>IN</sub> , V <sub>DD</sub>	Input Voltage		2.5		6	V
V <sub>IN,OFF</sub>	Minimum Voltage for Shutdown	V <sub>IN</sub> falling	2		2.2	V
V <sub>IN,ON</sub>	Maximum Voltage for Startup	V <sub>IN</sub> rising	2.2	2.2 2.4 V		V
I <sub>DD</sub>	Supply Current	PWM, V <sub>IN</sub> = V <sub>DD</sub> = 5V		400	500	μA
		EN = 0, V <sub>IN</sub> = V <sub>DD</sub> = 5V		0.1	1	μA
R <sub>DS(ON)-PMOS</sub>	PMOS FET Resistance	V <sub>DD</sub> = 5V, wafer test only		70	100	mΩ
R <sub>DS(ON)-NMOS</sub>	NMOS FET Resistance	V <sub>DD</sub> = 5V, wafer test only		45	75	mΩ
I <sub>LMAX</sub>	Current Limit			1.5		А
T <sub>OT,OFF</sub>	Over-temperature Threshold	T rising				°C
T <sub>OT,ON</sub>	Over-temperature Hysteresis	lysteresis T falling		130		°C
I <sub>EN</sub> , I <sub>RSI</sub>	EN, RSI Current	V <sub>EN</sub> , V <sub>RSI</sub> = 0V and 3.3V	-1		1	μA
V <sub>EN1</sub> , V <sub>RSI1</sub>	EN, RSI Rising Threshold	V <sub>DD</sub> = 3.3V			2.4	V
V <sub>EN2</sub> , V <sub>RSI2</sub>	EN, RSI Falling Threshold	V <sub>DD</sub> = 3.3V	0.8			V
V <sub>POR</sub>	Minimum $V_{FB}$ for POR, WRT Targeted $V_{FB}$ Value	V <sub>FB</sub> rising			95	%
		V <sub>FB</sub> falling	86			%
V <sub>OLPOR</sub>	POR Voltage Drop	I <sub>SINK</sub> = 5mA		35	70	mV
AC CHARACTE	RISTICS		I			
F <sub>PWM</sub>	PWM Switching Frequency	1.25		1.4	1.55	MHz
t <sub>RSI</sub>	Minimum RSI Pulse Width	Guaranteed by design		25	50	ns
t <sub>SS</sub>	Soft-start Time			650		μs
t <sub>POR</sub>	Power On Reset Delay Time		80	100	120	ms

# Pin Descriptions

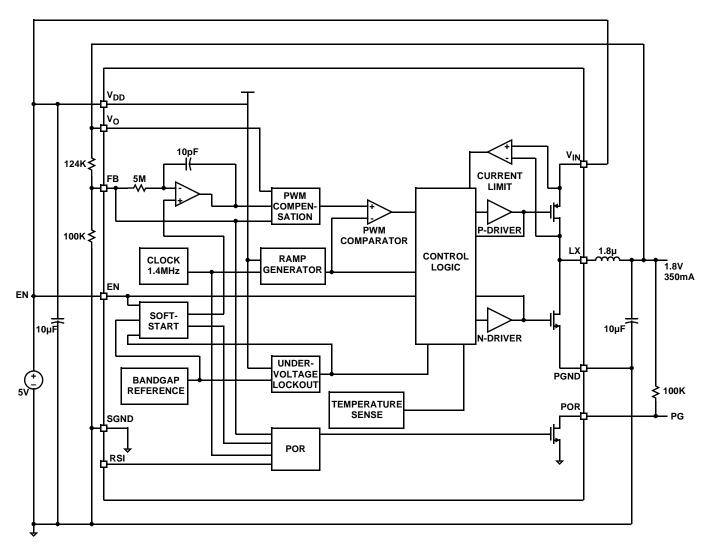
PIN NUMBER	PIN NAME	PIN FUNCTION	
1	SGND	Negative supply for the controller stage	
2	PGND	Negative supply for the power stage	
3	LX	Inductor drive pin; high current digital output with average voltage equal to the regulator output voltage	
4	VIN	Positive supply for the power stage	
5	VDD	Power supply for the controller stage	
6	RSI	Resets POR timer	
7	EN	Enable	
8	POR	Power on reset open drain output	
9	VO	Output voltage sense	
10	FB	Voltage feedback input; connected to an external resistor divider between $V_O$ and SGND for variable output	

# Timing Diagram

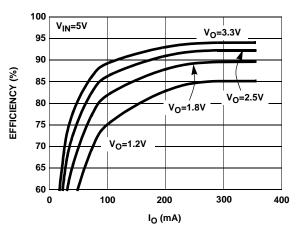


# EL7535

# Block Diagram







**FIGURE 1. EFFICIENCY** 

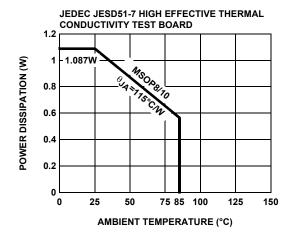


FIGURE 3. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

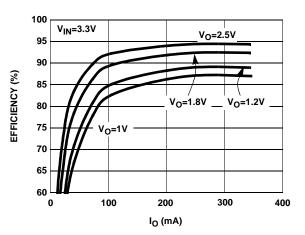


FIGURE 2. EFFICIENCY

JEDEC JESD51-3 LOW EFFECTIVE THERMAL CONDUCTIVITY TEST BOARD 0.6 607mW 0.5

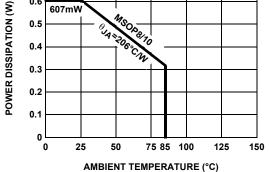


FIGURE 4. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

# Waveforms

All waveforms are taken at  $V_{IN}$ =3.3V,  $V_O$ =1.8V,  $I_O$ =350mA with component values shown on page 1, unless otherwise noted

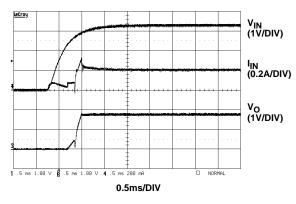


FIGURE 5. START-UP 1

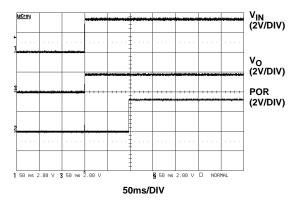
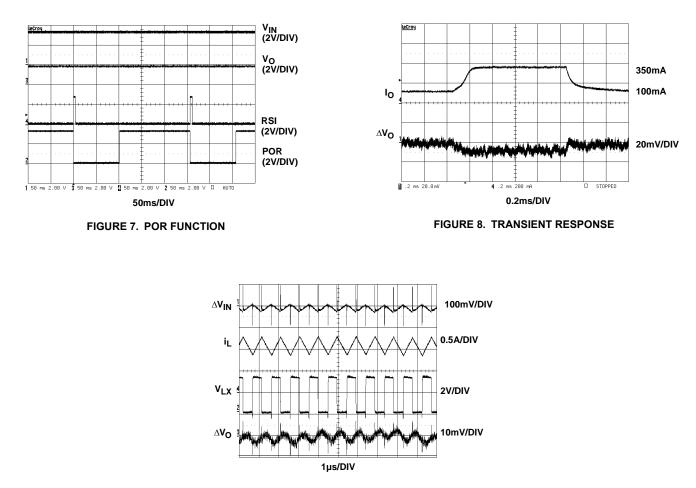


FIGURE 6. START-UP 2

# Waveforms (Continued)

All waveforms are taken at V<sub>IN</sub>=3.3V, V<sub>O</sub>=1.8V, I<sub>O</sub>=350mA with component values shown on page 1, unless otherwise noted





# Applications Information

### **Product Description**

The EL7535 is a synchronous, integrated FET 350mA stepdown regulator which operates from an input of 2.5V to 6V. The output voltage is user-adjustable with a pair of external resistors.

The internally-compensated controller makes it possible to use only two ceramic capacitors and one inductor to form a complete, very small footprint 350mA DC/DC converter.

### **PWM Operation**

In the PWM mode, the P channel MOSFET and N channel MOSFET always operate complementary. When the PMOSFET is on and the NMOSFET off, the inductor current increases linearly. The input energy is transferred to the output and also stored in the inductor. When the P channel MOSFET is off and the N channel MOSFET on, the inductor current decreases linearly, and energy is transferred from the inductor to the output. Hence, the average current through the inductor is the output current. Since the inductor and the output capacitor act as a low pass filter, the duty cycle ratio is approximately equal to  $V_O$  divided by  $V_{IN}$ .

The output LC filter has a second order effect. To maintain the stability of the converter, the overall controller must be compensated. This is done with the fixed internally compensated error amplifier and the PWM compensator. Because the compensations are fixed, the values of input and output capacitors are  $10\mu$ F to  $22\mu$ F ceramic. The inductor is nominally  $1.8\mu$ H, though  $1.5\mu$ A to  $2.2\mu$ H can be used.

### Start-Up and Shut-Down

When the EN pin is tied to  $V_{IN},$  and  $V_{IN}$  reaches approximately 2.4V, the regulator begins to switch. The

output voltage is gradually increased to ensure proper softstart operation.

When the EN pin is connected to a logic low, the EL7535 is in the shut-down mode. All the control circuitry and both MOSFETs are off, and  $V_{OUT}$  falls to zero. In this mode, the total input current is less than 1µA.

When the EN reaches logic HI, the regulator repeats the start-up procedure, including the soft-start function.

### **RSI/POR Function**

When powering up, the open-collector Power-On-Reset output holds low for about 100ms after V<sub>O</sub> reaches the preset voltage. When the active-HI reset signal RSI is issued, POR goes to low immediately and holds for the same period of time after RSI comes back to LOW. The output voltage is unaffected. (Please refer to the timing diagram). When the function is not used, connect RSI to ground and leave open the pull-up resister R<sub>4</sub> at POR pin.

The POR output also serves as a 100ms delayed Power Good signal when the pull-up resister  $R_4$  is installed. The RSI pin needs to be directly (or indirectly through a resister  $R_6$ ) connected to Ground for this to function properly.

### **Output Voltage Selection**

Users can set the output voltage of the converter with a resister divider, which can be chosen based on the following formula:

$$V_0 = 0.8 \times \left(1 + \frac{R_2}{R_1}\right)$$

### **Component Selection**

Because of the fixed internal compensation, the component choice is relatively narrow. For a regulator with fixed output voltage, only two capacitors and one inductor are required. We recommend  $10\mu$ F to  $22\mu$ F multi-layer ceramic capacitors with X5R or X7R rating for both the input and output capacitors, and  $1.5\mu$ H to  $2.2\mu$ H inductance for the inductor.

The RMS current present at the input capacitor is decided by the following formula:

$$I_{\text{INRMS}} = \frac{\sqrt{V_{\text{IN}} \times (V_{\text{IN}} - V_{\text{O}})}}{V_{\text{IN}}} \times I_{\text{O}}$$

This is about half of the output current  $I_O$  for all the  $V_O$ . This input capacitor must be able to handle this current.

The inductor peak-to-peak ripple current is given as:

$$\Delta I_{IL} = \frac{(V_{IN} - V_O) \times V_O}{L \times V_{IN} \times f_S}$$

· L is the inductance

• f<sub>S</sub> the switching frequency (nominally 1.4MHz)

The inductor must be able to handle  $I_O$  for the RMS load current, and to assure that the inductor is reliable, it must handle the 1.5A surge current that can occur during a current limit condition.

### **Current Limit and Short-Circuit Protection**

The current limit is set at about 1.5A for the PMOS. When a short-circuit occurs in the load, the preset current limit restricts the amount of current available to the output, which causes the output voltage to drop below the preset voltage. In the meantime, the excessive current heats up the regulator until it reaches the thermal shut-down point.

### Thermal Shut-Down

Once the junction reaches about 145°C, the regulator shuts down. Both the P channel and the N channel MOSFETs turn off. The output voltage will drop to zero. With the output MOSFETs turned off, the regulator will soon cool down. Once the junction temperature drops to about 130°C, the regulator will restart again in the same manner as EN pin connects to logic HI.

### **Thermal Performance**

The EL7535 is in a fused-lead MSOP10 package. Compared with regular MSOP10 package, the fused-lead package provides lower thermal resistance. The  $\theta_{JA}$  is 100°C/W on a 4-layer board and 125°C/W on 2-layer board. Maximizing the copper area around the pins will further improve the thermal performance.

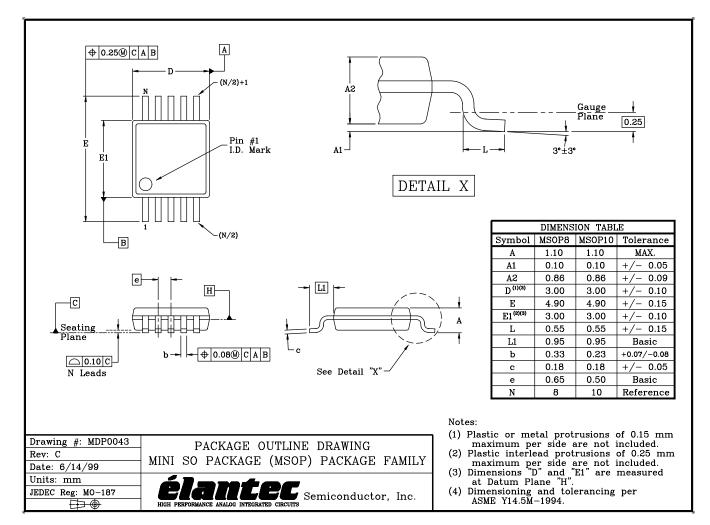
### Layout Considerations

The layout is very important for the converter to function properly. The following PC layout guidelines should be followed:

- Separate the Power Ground (↓) and Signal Ground (⊥); connect them only at one point right at the pins
- Place the input capacitor as close to  $\mathsf{V}_{\text{IN}}$  and PGND pins as possible
- · Make the following PC traces as small as possible:
  - from L<sub>X</sub> pin to L
  - from C<sub>O</sub> to PGND
- If used, connect the trace from the FB pin to R1 and R2 as close as possible
- · Maximize the copper area around the PGND pin
- Place several via holes under the chip to additional ground plane to improve heat dissipation

The demo board is a good example of layout based on this outline. Please refer to the EL7535 Application Brief.





NOTE: The package drawing shown here may not be the latest version. To check the latest revision, please refer to the Intersil website at <a href="http://www.intersil.com/design/packages/index.asp">http://www.intersil.com/design/packages/index.asp</a>

All Intersil U.S. products are manufactured, assembled and tested utilizing ISO9000 quality systems. Intersil Corporation's quality certifications can be viewed at www.intersil.com/design/quality

Intersil products are sold by description only. Intersil Corporation reserves the right to make changes in circuit design, software and/or specifications at any time without notice. Accordingly, the reader is cautioned to verify that data sheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.

For information regarding Intersil Corporation and its products, see www.intersil.com

